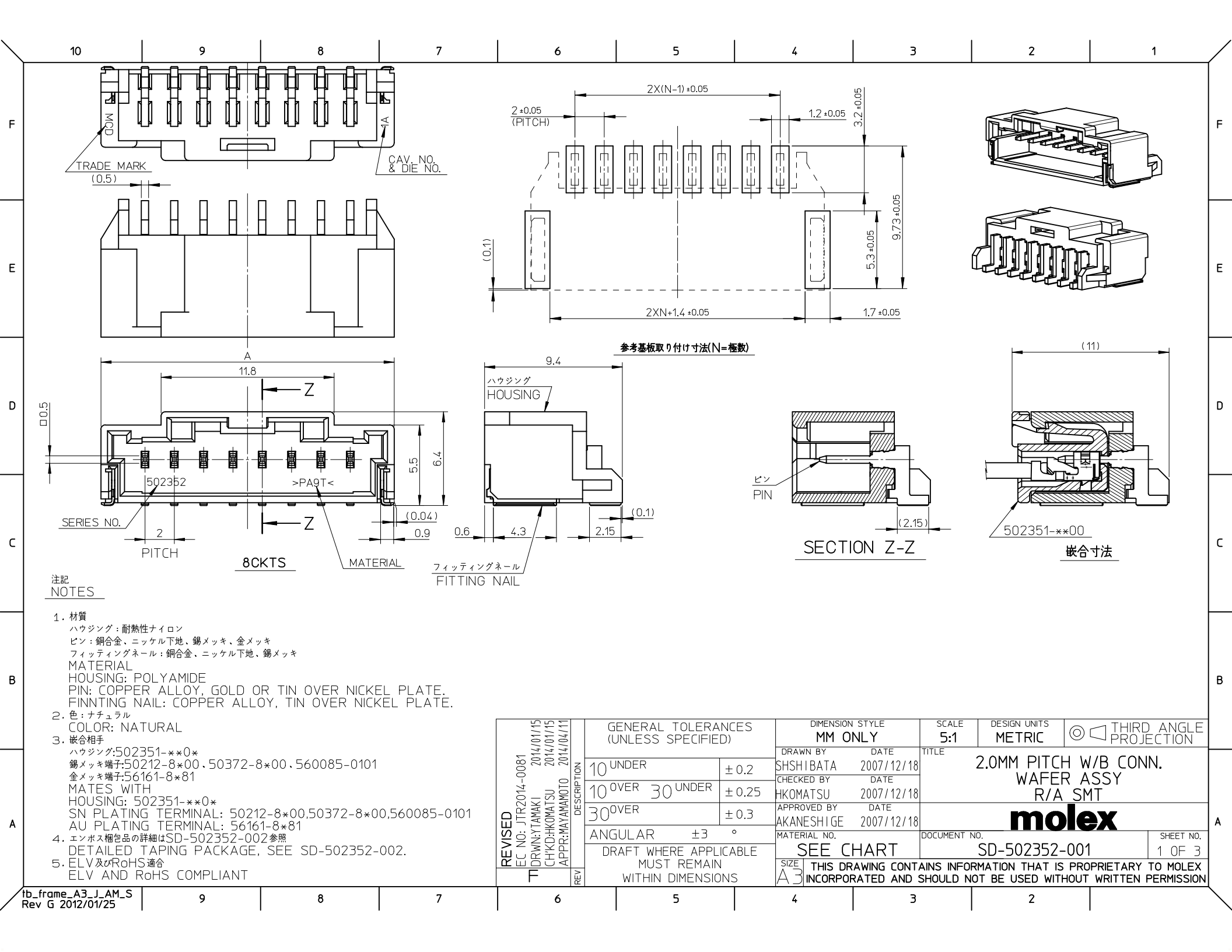




10				9				8				7				6				5				4				3				2				1			
F	Sn							15	Au									15																					
		32.0																																	14				
																																			13				
		28.0																																	12				
																																			11				
																																			10				
																																			9				
		20.0																																	8				
		18.0																																	7				
		16.0																																	6				
E		14.0																5																					
		12.0															4																						
		10.0															3																						
		8.0															2																						
PLATING	A	EMBOSSED PACKAGE ORDER NO.				CKTS	PLATING	A	EMBOSSED PACKGE ORDER NO.				CKTS																										
CONNECTOR SERIES NO. 502352-**08								CONNECTOR SERIES NO. 502352-**18																															

D

C

B

A

REVISED EC NO: JTR2014-0081 DRWN:YAMAKI 2014/01/15 CHKD:HKOMATSU 2014/01/15 APPR: MAYAMOTO 2014/04/11	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	TITLE 2.0MM PITCH W/B CONN. WAFER ASSY R/A SMT molex	
		10 UNDER	± 0.2	DRAWN BY SHSHIBATA	DATE 2007/12/18					
		10 OVER 30 UNDER	± 0.25	CHECKED BY HKOMATSU	DATE 2007/12/18					
		30 OVER	± 0.3	APPROVED BY AKANESHIGE	DATE 2007/12/18					
		ANGULAR ±3 °		MATERIAL NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		DOCUMENT NO. SD-502352-001	SHEET NO. 3 OF 3			
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

		10			9			8			7	6			5			4		3		2		1												
F	Sn	52.4	61.4	57.4	56	26.2	32.3	502352-1400	15	Au								15																		
		14	13	12	11	10			9									8									7	6	5	4	3	2	1			
		40.4	49.4	45.4	44	20.2	28.3	502352-1200	13		12	11	10	9	8	7	6	5									4	3	2	1						
									11		10	9	8	7	6	5	4	3									2	1								
									10		9	8	7	6	5	4	3	2									1									
									9		8	7	6	5	4	3	2	1																		
									8		7	6	5	4	3	2	1																			
									7		6	5	4	3	2	1																				
		E		28.4	37.4	33.4	32	14.2	18.3		502352-0700	7	28.4	37.4	33.4	32	14.2	18.3									502352-0710	7								
												16.3																502352-0600								
5	4									3									2	1																
29.4	25.4									24		11.5							14.3	502352-0500	5	14.3	502352-0510	5	12.3	502352-0410		4								
				4	3	2	1																													
				3	2	1																														
				2	1																															
PLATING	F			E	D	C	(B)	(A)	エンボス梱包品 製品番号 MATERIAL NO.		極数 CKT.	PLATING	F	E	D	C	(B)	(A)	エンボス梱包品 製品番号 MATERIAL NO.		極数 CKT.															

D

C

B

A

REVISED EC NO: JTR2014-0025 T DRWN:YAMAKI 2013/09/12 CHKD:HKOMATSU 2013/09/12 APPR:MAYAMOTO 2013/09/13	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION
		10 UNDER	± 0.2	DRAWN BY SHSHIBATA	DATE 2007/6/6	TITLE 2.0MM PITCH W/B CONN. WAFER ASSY EMBOSSED TAPE PACKAGE		
		10 ^{OVER} 30 UNDER	± 0.25	CHECKED BY TAITO	DATE 2007/6/6			
		30 ^{OVER}	± 0.3	APPROVED BY MAYAMAMOTO	DATE 2012/03/14			
		ANGULAR ±1 °		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-502352-002	SHEET NO. 2 OF 2	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

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C

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A